



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

DN 51343

In re application of:
Seita et al.

Serial No.: 10/027,919

Filed: December 20, 2001

For: ELECTROLYTIC COPPER PLATING
SOLUTION AND METHOD FOR
CONTROLLING THE SAME

: Group Art Unit: 1753

: Examiner: Edna Wong

10/A
w.m.
6/24/03

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

In response to the Official Action mailed on March 11, 2003, Applicants submit the following amendments and remarks.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the claims are reflected in the listing of claims which begins on page 5 of this paper.

Remarks begin on page 9 of this paper.